



DATA SHEET

● DEVICE NUMBER : BL-H3G632L-TRB

SHEET DATE	1	2	3	4	5	6	7				CONTENTS
2010.10.20	1.0	1.0	1.0	1.0	1.0	1.0	1.0				Original Released

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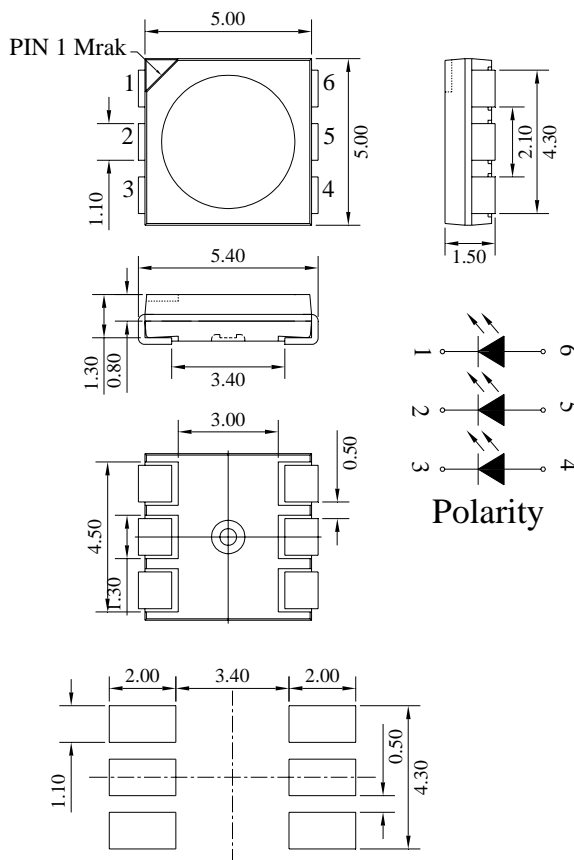
● Features:

1. Emitted Color: Super Green.
2. Lens Appearance: Water Clear.
3. 5.4x5.0x1.5mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

● Applications:

1. Automotive lighting.
2. Backlighting: LCDs, Key pads advertising.
3. Status indicators: Consumer & industrial electronics.
4. General use.

● Package Dimensions:



NOTES:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.10\text{mm}$ (0.004") unless otherwise specified.
3. Specifications are subject to change without notice.

● Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation ^{*1}	P_D	360	mW
Forward Current ^{*1}	I_F	90	mA
Peak Forward Current ^{*2}	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	$-40^\circ\text{C} \sim 100^\circ\text{C}$	-
Storage Temperature	T_{stg}	$-40^\circ\text{C} \sim 100^\circ\text{C}$	-
Soldering Temperature	T_{sol}	See Page 6	-

^{*1} The values are based on 3-circuit performance

^{*2} Condition for I_{FP} is pulse of 1/10 duty and 3 msec width.

Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage ^{*1}	V_F	$I_F=20\text{mA}$	-	3.3	3.6	V
Luminous Intensity ^{*2}	I_v	$I_F=60\text{mA}$	-	3000	-	mcd
Peak Wavelength	λ_p	$I_F=60\text{mA}$	-	525	-	nm
Dominant Wavelength	λ_d	$I_F=60\text{mA}$	520	-	530	nm
Spectral LineHalf-width	$\Delta \lambda$	$I_F=60\text{mA}$	-	30	-	nm
Reverse Current	I_R	$V_R=5\text{V}$	-	-	10	μA
Viewing Angle	$2\theta_{1/2}$	$I_F=60\text{mA}$	-	120	-	degree

*¹ The values are based on 1-circuit performance

*² The values are based on 3-circuit performance

Typical Electro-Optical Characteristics Curves.

Fig.1 Relative intensity vs. wavelength

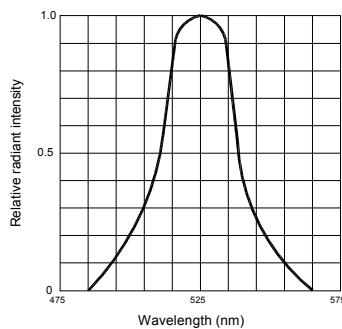


Fig.2 Forward current derating curve vs. ambient temperature

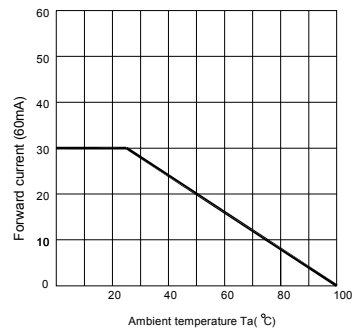


Fig.3 Forward current vs. forward voltage

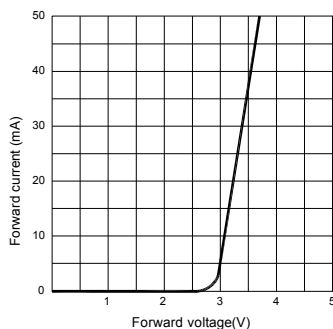


Fig.4 Relative luminous intensity vs. ambient temperature

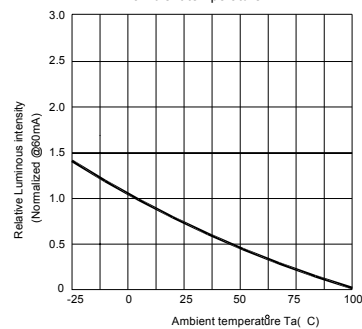


Fig.5 Relative luminous intensity vs. forward current

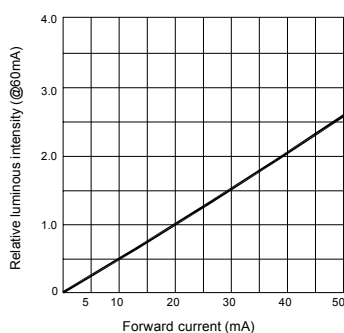
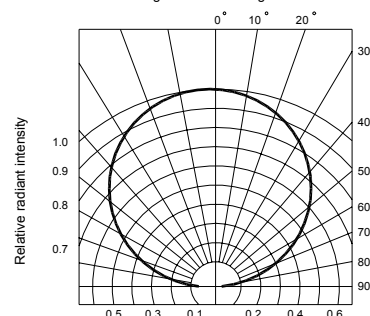
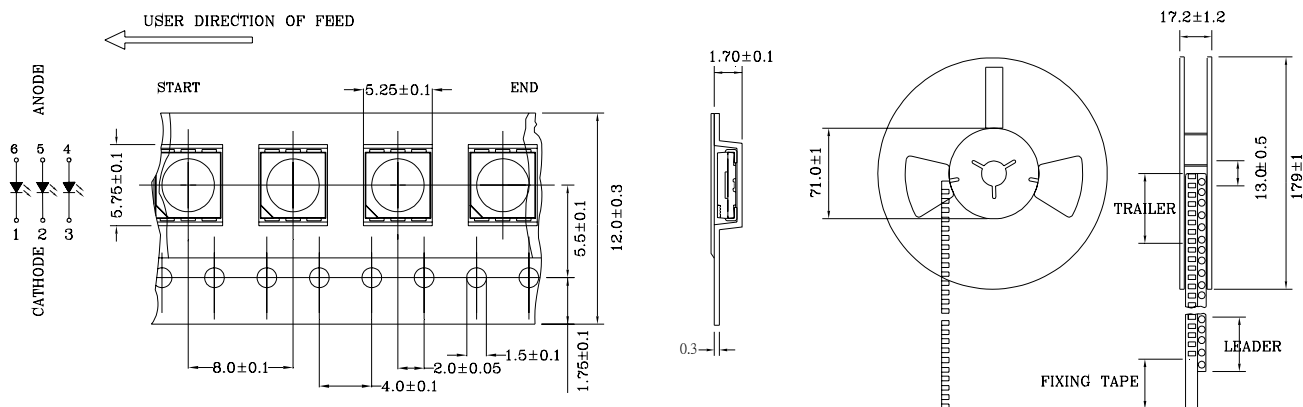


Fig.6 Radiation diagram

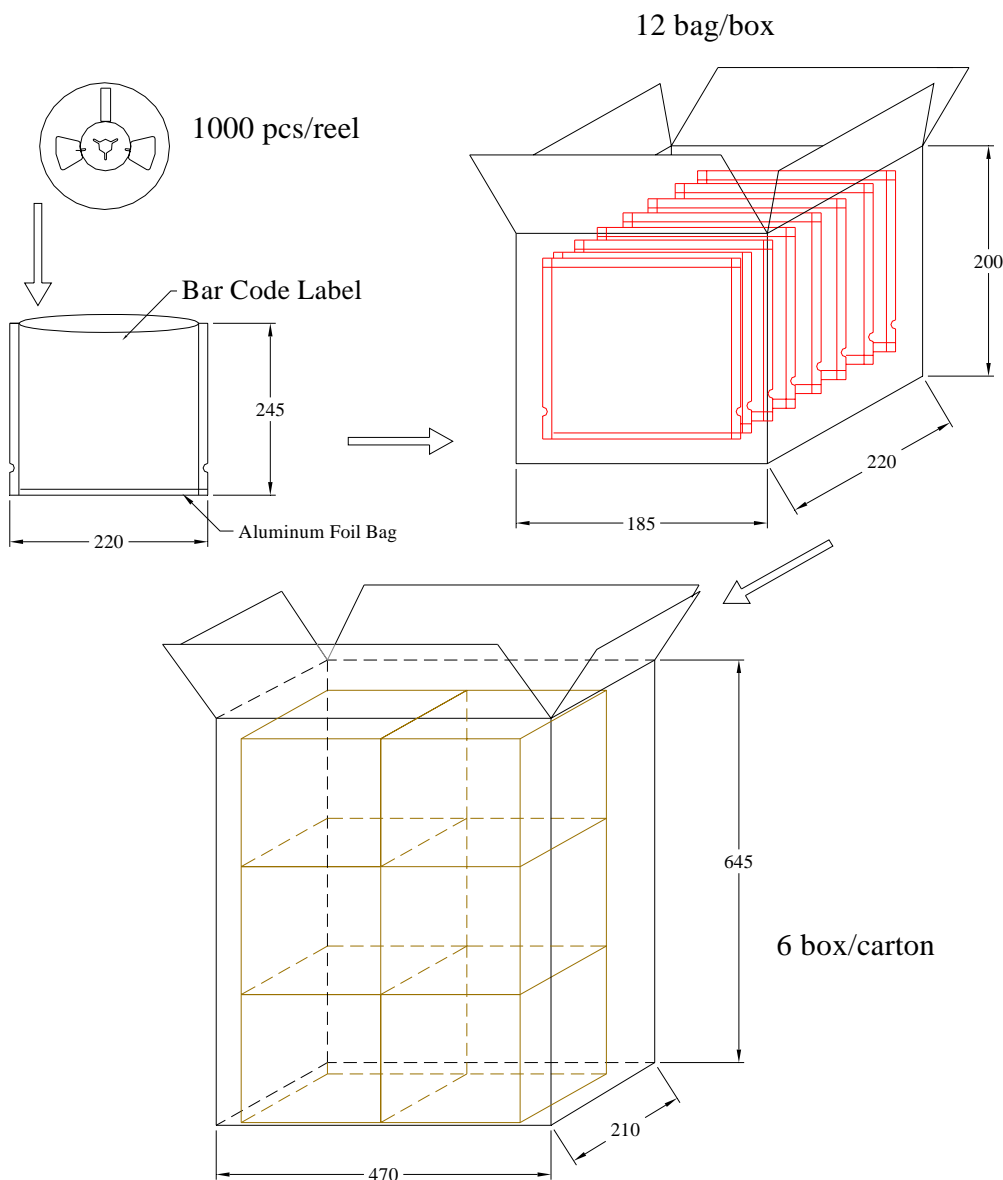


● Tapping and packaging specifications(Units: mm)



NOTE:1000 PCS PER REEL

● Package Method:(unit:mm)



● **Bin Limits**

Intensity Bin Limits (At 60mA. The values are based on 3-circuit performance)

BIN CODE	Min. (mcd)	Max. (mcd)
X	1600	2400
Y	2400	3700
Z	3700	5550

Tolerance for each Bin limit is $\pm 10\%$

Color Bin Limits (At 60 mA)

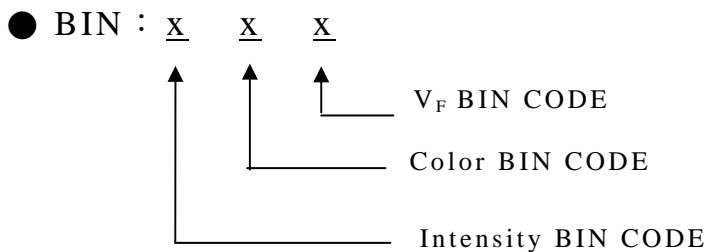
BIN CODE	Min. (nm)	Max. (nm)
6	520	525
7	525	530

Tolerance for each Bin limit is $\pm 1\text{nm}$

Forward Voltage Bin Limits (At 60 mA)

BIN CODE	Min.(V)	Max.(V)
G	2.8	3.0
H	3.0	3.2
J	3.2	3.4
K	3.4	3.6

Tolerance for each Bin limit is $\pm 0.5\text{V}$



● Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	I _F =20mA Ta=Under room temperature Test time=1,000hrs	0/20
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+65°C±5°C RH=90%-95% Test time=240hrs	0/20
	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+85°C±5°C Test time=1,000hrs	0/20
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-35°C±5°C Test time=1,000hrs	0/20
Environmental Test	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	-35°C ~ +25°C ~ +85°C ~ +25°C 60min 20min 60min 20min Test Time=5cycle	0/20
	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	-35°C±5°C ~ +85°C±5°C 20min 20min Test Time=10cycle	0/20
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating : 140°C-160°C, within 2 minutes. Operation heating : 260°C (Max.), within 10seconds. (Max.)	0/20

● Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V _F (V)	I _F =60mA	Over U ¹ x1.2
Reverse current	I _R (uA)	V _R =5V	Over U ¹ x2
Luminous intensity	I _v (mcd)	I _F =60mA	Below S ¹ X0.5

Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. After each test, remove test pieces, wait for 2 hours and test pieces have returned to ambient temperature, then take next measurement.

● Soldering :

1. Manual Soldering

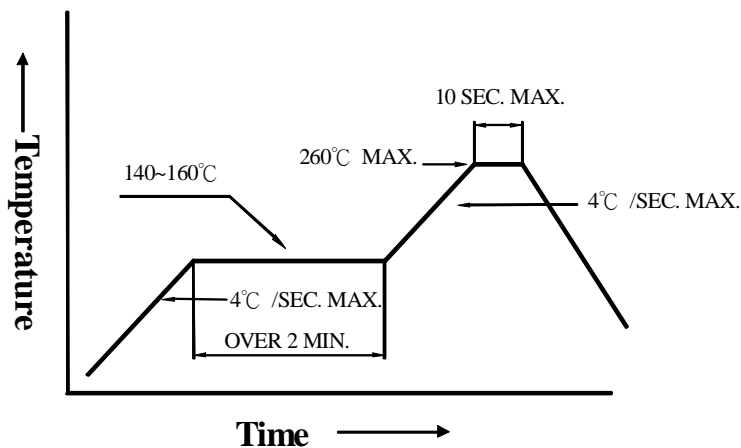
The temperature of the iron tip should not be higher than 350°C and Soldering time to be within 3 seconds per solder-pad.

2. Reflow Soldering

Preheating : 140°C~160°C ±5°C ,within 2 minutes.

Operation heating : 260°C (Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

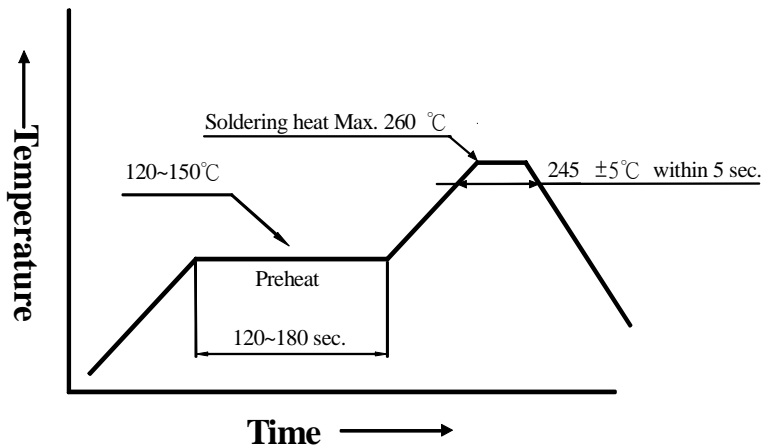


3. DIP soldering (Wave Soldering) :

Preheating : 120°C~150°C ,within 120~180 sec.

Operation heating : 245°C±5°C within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).



● Handling :

Care must be taken not to damage LED's epoxy resin while exposing to high temperature or contact LED's epoxy resin with hard or sharp objects, such as metal hook, tweezer or sand blasting.

● Notes for designing:

Current limiting resistor must be used in the circuit to drive BRIGHT LEDs within the rated figures and not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF cycles. When using pulse driving, the average current must be within the rated figures. And the circuit should be designed to avoid reverse voltage when turning off the BRIGHT LEDs.

● Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C -30°C (41°F) Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
 - a. Completed within 168 hours.
 - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
 - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
 - 48 hours at 60°C±3°C.

● Package and Label of Products:

- (1) Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:

